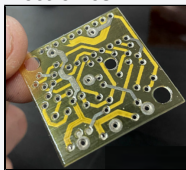


Multi-layer film forming

APPLICATIONS		KNOWLEDGE & MODELS		CAPABILITIES	
Electronics 	IC substrate manufacturing	Process	Vacuum Hot Press	Core Equipments at ADL Ewha Site	
Film formation		Material	Polyimide Film	Hot Press Machine	
			Cu Foil		
		Prepreg			
		Simulation (VE)	bending of FCCL		
Core Competitiveness at ADL Ewha		Evaluation Data Library		Project History	
Film Lamination Processing of Microelectronics		Customized Products	Liquid Crystal Polymer Products		
				No	Project Title
				1	Flexible Copper Clad Laminate development
				2	
				3	